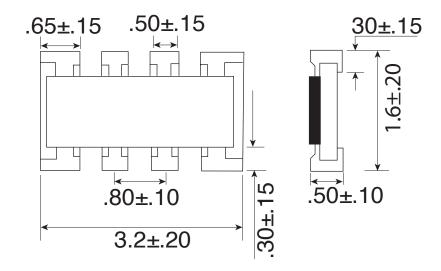


1% or 5% Thick Film Chip Resistor Array -Convex Terminal

304-TFRA4 Series

Date Last Revised: 1/22/20

DIMENSIONS: mm

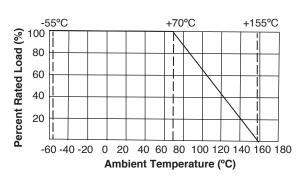


■ PART NUMBERING SYSTEM

3 0 4 -	T F R A 4	- 1 -	1 0 0	- R C
Prefix	Series	Tolerance	Value	Suffix (RoHS Compliant)

SPECIFICATIONS:				
Power Rating (Watts)	0.0625W(1/16W)			
Max.Working Voltage	50V			
Max.Overload Voltage	100V			
Dielectric Withstanding Voltage	300V			
Temperature Range	-55°C~+155°C			
Ambient Temperature	70°C			





NOTES:

· Nominal Resistance

Effective figures of nominal resistance shall be in accordance :

- •E-24 and E-96 series for 1%
- •E-24 series for 2% and 5%
- •Resistance Range : $1\Omega \sim 1M\Omega$
- •RoHS Compliant

Available from Mouser Electronics 1-800-346-6873 / www.mouser.com

1% or 5% Thick Film Chip Resistor Array-Convex Terminal

Characteristics	Limits	Test Methods (JIS C 5201-1)	
Temperature coefficient	Refer to item 5	Natural resistance change per temp. degree centigrade. R ₂ -R ₁ x ₁₀ ⁶ (PPM/°C) R ₁ (t ₂ -t ₁) R ₁ : Resistance value at room temperature (t ₁) R ₂ : Resistance value at room temp.plus 100°C (t ₂)	
Short time overload	Resistance change rate is $\pm 5\%(2.0 \% + 0.1\Omega)$ Max. $\pm 1\%(1.0 \% + 0.1\Omega)$ Max.	Permanent resistance change after the application of a potential of 2.5 times RCWV for 5 seconds.	
Insulation resistance	1,000M Ω or more	Apply 500V DC between protective coating and termination for 1 minute, then measure	
Dielectric withstanding Voltage	No evidence of flashover mechanical damage, arcing or insulation break down	Clamped in the trough of a 90° metallic V-block and shall be tested at AC potential respectively specified in the table 1.for 60+10/-0 secs.	
Terminal bending	Resistance change rate is ±(1.0% +0.05Ω) Max.	Twist of Test Board: Y/X=5/90mm for 10 seconds	
*Solderability	95% coverage Min.	Test temperature of solder: 245 ± 3°C Dipping them solder: 2-3 seconds (Sub-clause 4.17)	
Soldering temp. reference	Electrical characteristics shall be satisfied. Without distinct deformation in appearance. (95% coverage Min.)	Wave soldering condition: (2 cycles Max.) Pre-heat: 100 ~ 120 °C, 30 ± 5 sec. Suggestion solder temp.: 235 ~ 255 °C, 10 sec. (Max.) Peak temp.: 260 °C Reflow soldering condition: (2 cycles Max.) Pre-heat: 150 ~ 180 °C, 90 ~ 120 sec. Suggestion solder temp.: 235 ~ 255 °C, 20 ~ 40 sec. Peak temp.: 260 °C (°C) 250 200 150 Peak: 260 °C (Max) 235 °C - 255 °C - 20 ~ 40 sec. Peak temp.: 260 °C Temperature profile for evauation Hand soldering condition: The soldering iron tip temperature should be less than 300 °C and maximum contract time should be 5 sec.	